From Technologies to IP Business Intelligence

Gan Electronics (Power & RF applications) From materials to devices, modules & circuits

Patent Landscape Analysis

November 2023



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mmmi C-meme

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- Power circuits & applications

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- Patent landscape overview
 - Who is driving the patenting activity?
 - The global supply chain from a patent perspective
 - Most active IP players and new entrants

- Main technical challenges (dynamic on-resistance, e-mode, GaN-on-Si, vertical devices, monolithic integration, thermal management, etc.)

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For each country: time evolution of patenting activity, supply chain from a patent perspective, status of players' IP activity, main patent assignees, most active IP players, new entrants, main technical challenges addressed by IP players, IP strategies of players, current legal status of their patents (pending, granted, protected countries, etc.), recent IP collaborations (patent co-filings) and IP transfers (change in ownership), focus on key players' patent portfolio.

• Patent landscape analysis by supply chain segments

353
363
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For each segment: Time evolution of patent publications from US players, Japanese players, European players, etc., main patent assignees, most active IP players, new entrants, current legal status of their patents (pending, granted), technical challenges addressed by IP players, main patent assignees and new entrant by technical challenge.

Terminology

ANNEX

KNOWMADE PRESENTATION

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SANAD

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INTRODUCTION Context and objectives of the report

Power GaN

- > The power GaN industry landscape has been reshaped by acquisitions of startup companies and partnerships between well-established players in the power electronics industry.
- > The application base for GaN technology is widening. The adoption of GaN power devices in replacement for Si power devices is accelerating, especially in consumer applications.
- > Well-established GaN players and newcomers announced the development of high-voltage GaN technology to compete with Si IGBT and SiC MOSFET in EV applications.
- > New companies have entered the power GaN market recently or announced their intention to enter this market shortly.
- > Early market players look to consolidate their leadership amid growing competition worldwide and geopolitical tensions escalating between US and China.
- > As a countermeasure to US trade sanctions, China is driving the development of a domestic supply chain to serve its own market.

RF GaN

- > The RF GaN industry landscape has been reshaped by acquisitions and partnerships (IP, manufacturing) between well-established players in the RF industry.
- > The deployment of 5G base stations is driving the RF GaN market, with GaN-on-SiC RF devices progressively replacing Si LDMOS in the telecom infrastructure.
- > There is a growing interest for RF GaN-on-Si devices as the telecom infrastructure evolves toward lower power and higher frequencies (e.g., 6G applications).
- The opportunity to offer RF GaN technology at lower cost by leveraging the existing Si manufacturing lines and the GaN-on-Si platform is expected to drive the emergence of new players in the RF GaN market.
- RF GaN-on-Si technology is now close to enter the market. Yet many technical challenges remain to be solved for the large-scale adoption of the RF GaN-on-Si platform (incl. reliability, process maturity and scalability).
- Regardless of the platform, innovations at all levels from epitaxy to devices, packaging and circuits are still strongly required to fully unlock the potential of GaN technology in RF applications.
- > In the field of telecommunications, US government has recently banned new equipment from Chinese players such as Huawei and ZTE, citing national security risk.

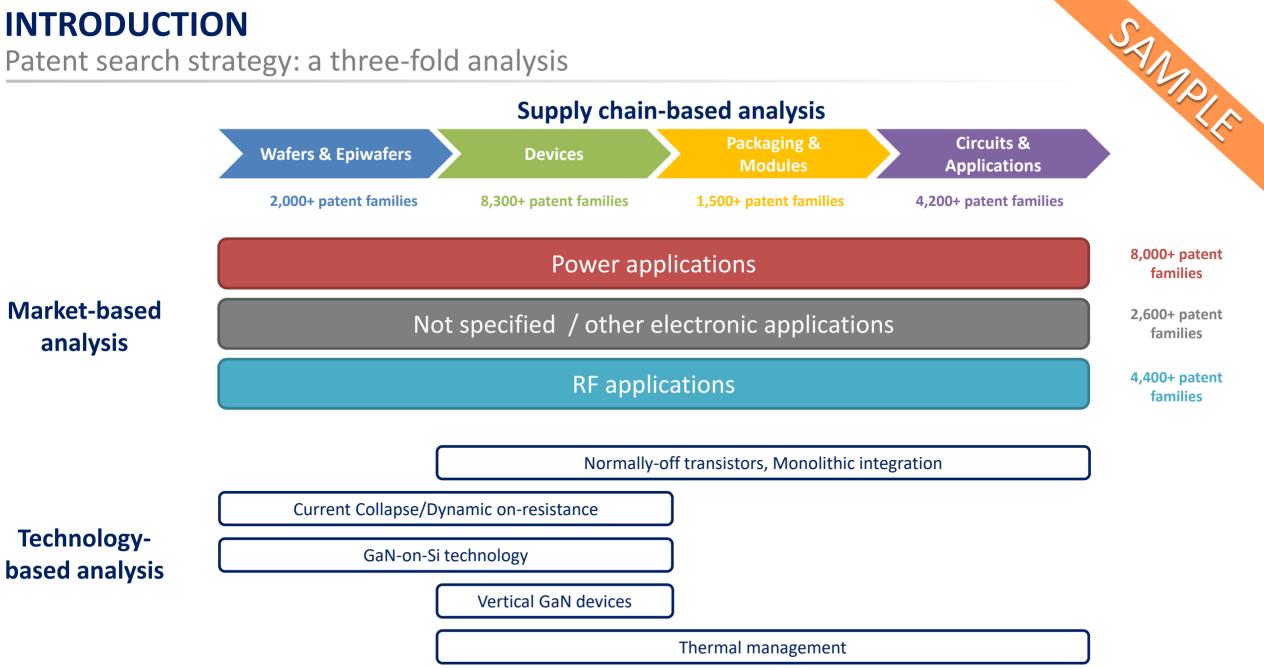
In this context, this GaN Electronics Patent Landscape report aims to understand what is the strategy of players to consolidate their position in the emerging power and RF GaN markets and to limit the risks and uncertainties related to the adoption, industrialization and commercialization of a new power and RF semiconductor technologies (investment, geopolitical and IP risks).

What's more, the report identifies well-established IP players, IP challengers and newcomers, which are not yet in the power or RF GaN markets and thereby may represent either a threat (future IP and market challengers) or an opportunity to access external innovation (M&A targets, partnerships, IP licensing), depending on the perspective.

Eventually, the report positions early market players in the global IP competition, as these players are the most likely to assert their patents against new players entering the power or RF GaN markets, to maintain and expand their market leadership.

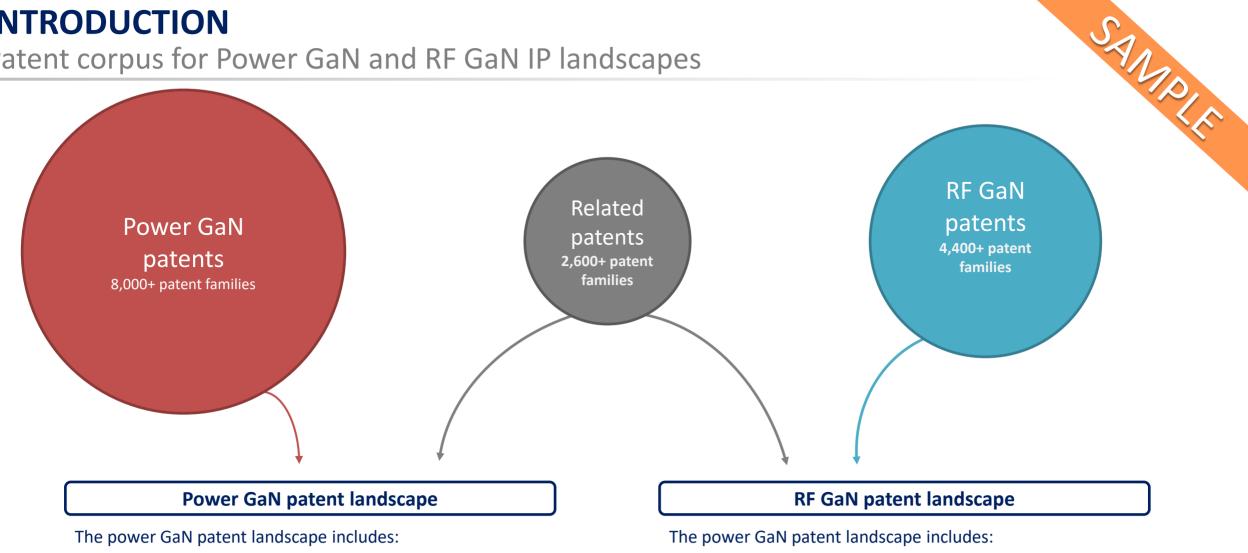
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Patent search strategy: a three-fold analysis



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Patent corpus for Power GaN and RF GaN IP landscapes



> All power GaN patents

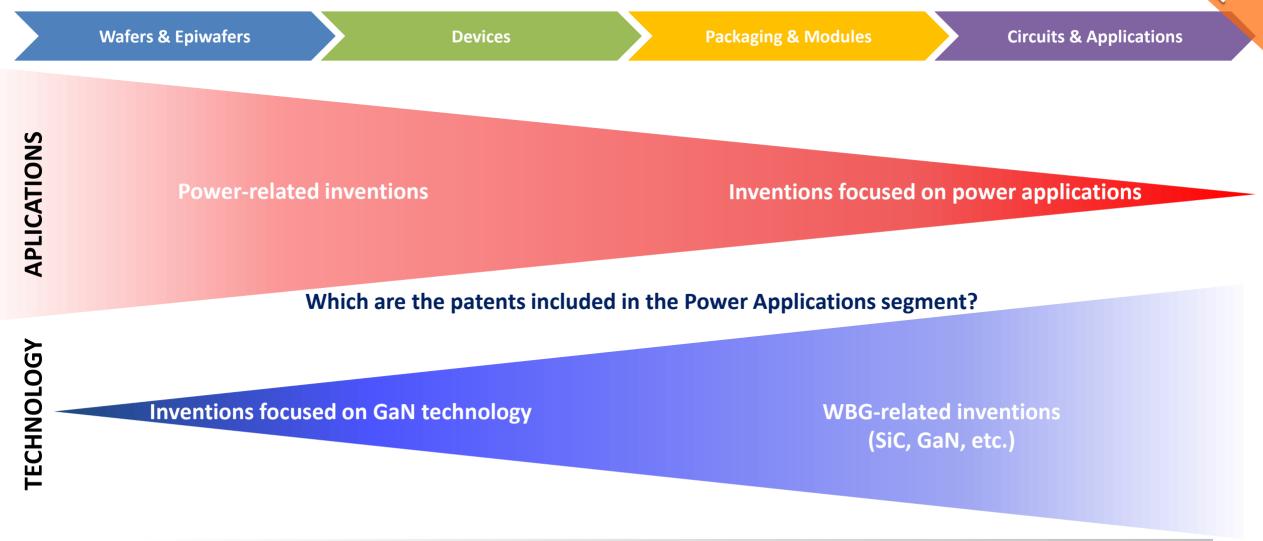
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- > Related GaN electronics patents from IP players owning power GaN patents
- \rightarrow 10,400+ patent families in the power GaN patent landscape

- > All **RF GaN patents**
- > Related GaN electronics patents from IP players owning RF GaN patents
- \rightarrow 6,500+ patent families in the RF GaN patent landscape

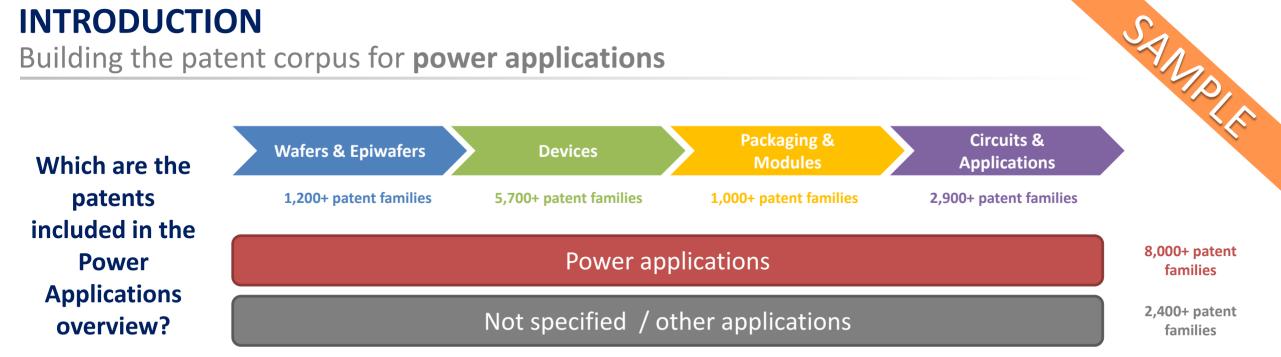
Power GaN patent selection: Focus of the invention depends on its position on the supply chain

Due to different strategies of patent filings across the supply chain, the scope of the patent selection must be tuned according to the position in the supply chain:





INTRODUCTION Building the patent corpus for **power applications**



All the patents focused on power applications (8,000+ patent families)

\rightarrow 77% of the Power GaN Electronics patent corpus

The nonspecific/generic GaN Electronics patents assigned to IP players with several patents focused on power applications (2,400+ patent families)

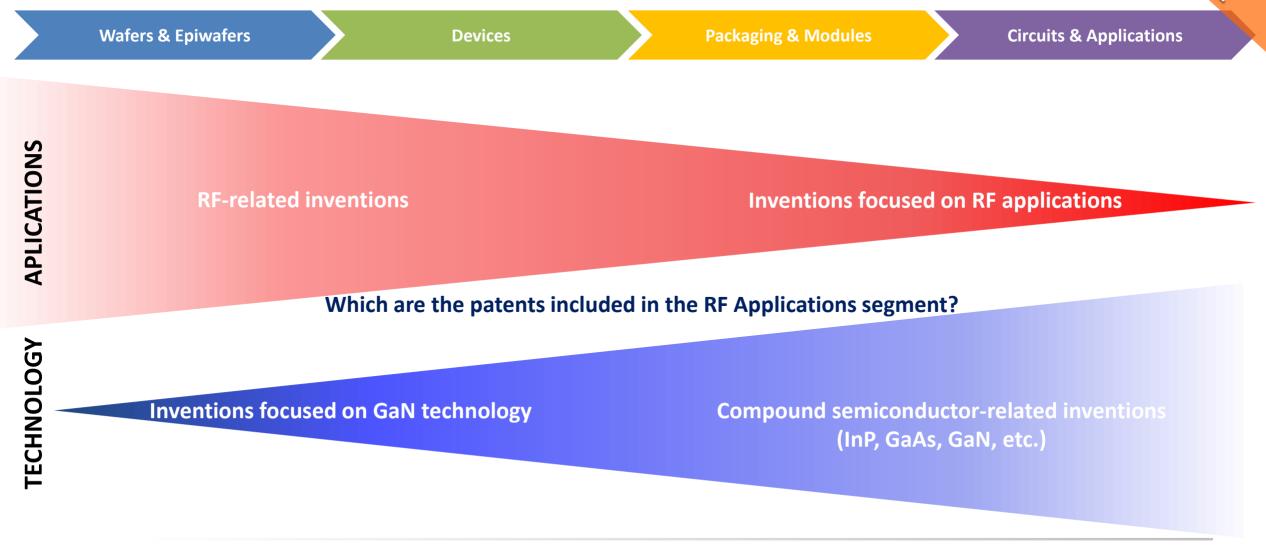
 \rightarrow 23% of the Power GaN Electronics patent corpus

This approach aims to provide a more comprehensive view of the patenting activities of IP players in the Power GaN competitive landscape.



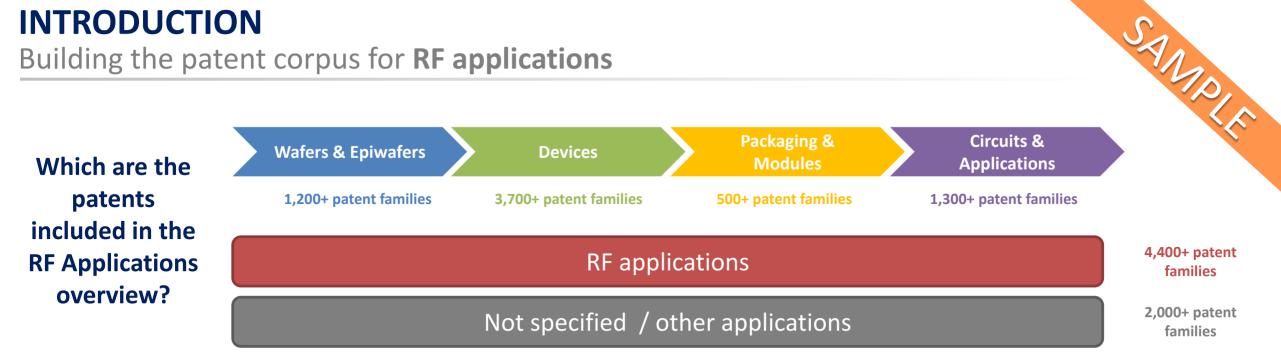
RF GaN patent selection: Focus of the invention depends on its position on the supply chain

Due to different strategies of patent filings across the supply chain, the scope of the patent selection must be tuned according to the position in the supply chain:



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INTRODUCTION Building the patent corpus for **RF applications**



All the patents focused on power applications (4,400+ patent families)

\rightarrow 69% of the RF GaN Electronics patent corpus

The nonspecific/generic GaN Electronics patents assigned to IP players with several patents focused on RF applications (2,000+ patent families)

 \rightarrow 31% of the RF GaN Electronics patent corpus

This approach aims to provide a more comprehensive view of the patenting activities of IP players in the RF GaN competitive landscape.

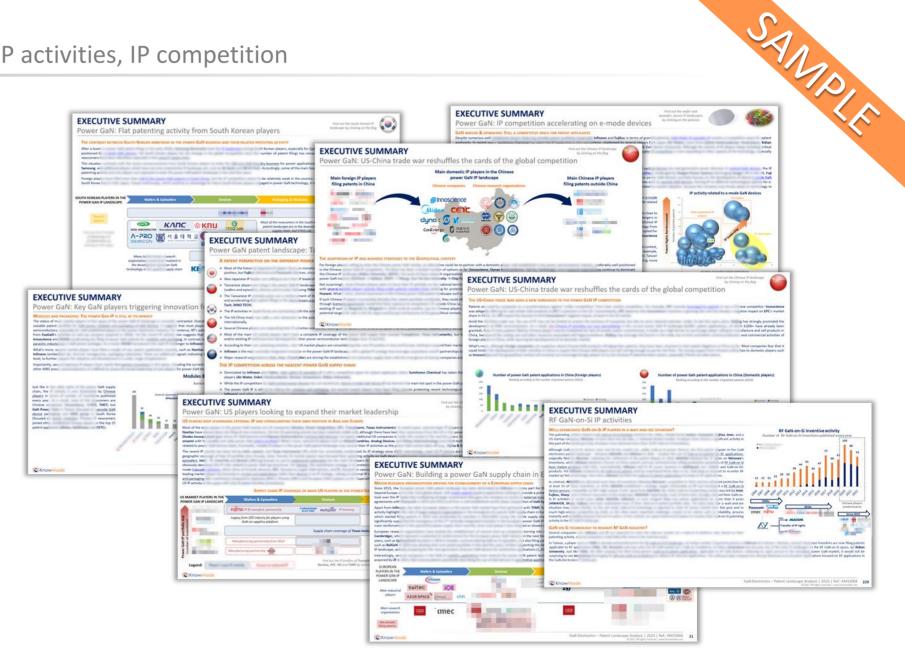


Executive summary Take away messages, IP leaders, IP activities, IP competition

- Take away messages
- IP leaders

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- Players ramping up their IP activities
- •New IP players reshaping the landscape
- Global IP competition
- IP activities in the different ecosystems (Japan, China, US, Europe, Taiwan, South Korea)
- IP activities across the supply chain (wafer & epiwafers, device, module & packaging, circuit & applications)
- Key players triggering innovations





Excel file with all patents analyzed in the report

Useful patent database allows multi-criteria searches

With the present report is provided an extensive Excel database with the 15,000+ patent families (inventions) analyzed in this study. In useful patent database allows for multicriteria searches and includes patent publication numbers, hyperlinks to an updated online database (original documents, legal status, etc.), priority date, title, abstract, patent assignees, patent's current legal status, and segments (power applications, RF applications, wafers & epiwafers, devices, modules & packaging, circuits, dynamic on-resistance, e-mode, GaN-on-Silicon, monolithic integration, thermal management, vertical devices, etc.).

			APPLICATION				SUPPL	Y CHAIN				TECHNICA	LSEGMENT			
signee name used in the report	Title	Abstract	Power	Related patents selected for the Power GaN IP landscape	RF	Related patents selected for the RF GaN IP Jandscape 🖵	Wafers & Epiwafers ▼	Devices T	Modules & Packaging	Circuits & Applications	Dynamic on- resistance	e-mode	GaN-on-Si	Monolithic integration	Thermal management	Yertical device
BAISHI ELECTRONIC TECHNO	(CN114823853) Nitride semiconductor epitaxial structure	(CN114823853) The invention discloses a nitride semiconductor epitaxial structure, which		x			x	_							_	_
NUO MICROELECTRONICS VU	(CN110620143) Hybrid channel compound semiconductor device	(CN110620143) The invention discloses a hybrid channel compound semiconductor device. A	x					x				x				
Innoscience	(WO2023123378) Semiconductor device and method for	(W02023/123378) A semiconductor device includes a first and a second nitride-based semiconductor		x		x		x								
CoolSemi	(CN115117150) GaN HEMT power device and preparation method	(CN115911096) The invention discloses a GaN HEMT power device for realizing a CASCODE	x					x		×		x				
Mitsubishi Electric	(WO202244123) Drive control circuit for power semiconductor	(WO2022/044123) According to the present invention, a gate current detector (8) detects a gate	x							x						
Georgia Tech	(US11469726) Highly efficient dual-drive power amplifier for high	(US20230084449) A dual-drive power amplifier (PA) where the PA core includes a differential pair of			x					×						
Innoscience	(WO2023137588) Nitride-based bidirectional switching device for	(W02023/137588) A nitride-based bidirectional switching device is provided for working with a	x							×	Seg	7 m e	nte			
CTM MAGNETICS	(US3530486) Distributed gap inductor filter apparatus and	(US20150310977) The invention comprises a high frequency inductor filter apparatus and method of	×							×	26		1169			
Innoscience	(US20220199817) Semiconductor device and method for	Patent infor	ma	tion				x		Applic	ations:	nower	nowar-	rolatod		
CoolSemi	(CN114883336) Recessed Fin-JFET gate structure HEMT and		IIIa	CIOI				x				~ ~ ~				
Sony	(WO2022219861) Semiconductor device a Diattos	and numbers of priority/appl	ication	/nublica	tion	trant	x			pate	ents, RF,	RF-rela	ated pat	tents		
Enkris Semiconductor	Semiconductor structure and preparation method	A semiconductor structure and a preparation method for a semiconductor		/ pupilea				x					×			x
Enkris Semiconductor	(W02022217541) Semiconductor structure and preparation method	The present decisions provided and Title, abstract, of	claims	x		×	x			C	hu ah ai a		×			
Ampleon	(CN115207094) Semiconductor device and method of	Patent applicants, current as	ssignee	s. invent	ors			x			ly chain					
HC Semitek	()				X		x			devices,	module	s & pac	kaging,	circuits	&	
bsound Electronic Industrial	Environment-friendly high-fidelity gallium nitride	legal status of patents (grant	tea, pei	naing, ex	cpired	, etc.)				×		plicatio				
Shanghai Dianji University	(CN115208215) Wireless power transmission distance	(CN115208215) The invention relates to a wireless electric energy transmission distance	×							×	ab	pheatic				
HC Semitek	(CN115207083) Epitaxial structure of radio frequency device for	Hyperlinks to an updated	online	datahasi	×		x									
GiantSun Power	Intelligent distribution circuit for blind mating of	The invention discloses a double PD port blind mating intelligent distribution	omine	uatabas	<u> </u>					Techr	nical cha	llenges	: dvnan	nic on-		
nal Yang Ming Chiao Tung Ui	Synchronous buck converter using a single gate	A synchronous buck converter using a single gate drive control is provided and	×							×						
Toyota Group	(JP2022153018) Manufacturing method for nitride semiconductor	(JP2022153018) PROBLEM TO BE SOLVED: To provide a technique of activating impurities (IP2022150414)	x					x			nce, e-r					
Fujitsu	(JP2022152043) Nitride semiconductor device and manufacturing (W02022217056)	(JP2022152043) PROBLEM TO BE SOLVED: To provide a nitride semiconductor device in which (WO2022/21056)		x		x		x		mon	olithic i	ntegrat	ion, the	ermal		
Murata / pSemi Murata / pSemi	Circuit assembly including gallium nitride devices (W02022217057)	(W02022/217056) A circuit assembly includes a first printed circuit basend (PCB), a switching device (W02022/217057) A circuit assembly includes a printed circuit board (PCB) with a metal inlav and an	x							X	nageme				×	
aN Electronics - PATI		o currant assembly includes a burited circuit poard [herb] with a type(a) itiply and an														



Patent landscape overview

General trends, key patent assignees and newcomers along the power supply chain

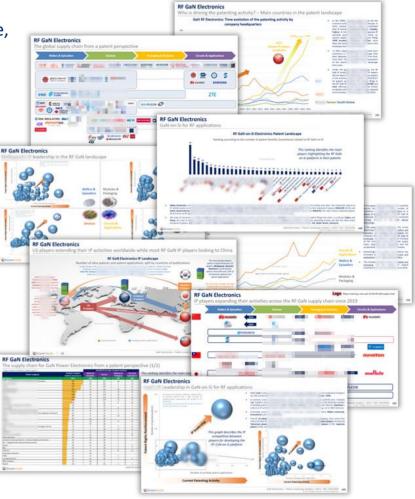


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Who is driving the patenting activity?
The global supply chain from a patent perspective.
Most active IP players and new entrants.
Main technical challenges (dynamic on-resistance, e-mode, GaN-on-Si, vertical devices, monolithic integration, thermal management, etc.).

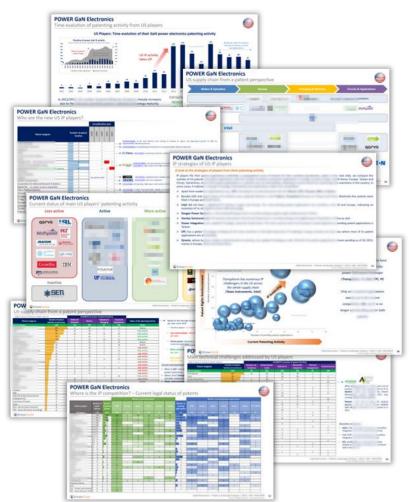


SANADIA



IP dynamics, IP supply chain, IP strategies of players, main technical challenges, IP newcomers





AMERICAN PLAYERS

Time evolution of patenting activity. Supply chain from a patent perspective. Status of players' IP activity.

Main patent assignees. Most active IP players and new entrants. Main technical challenges addressed by IP players. IP strategies of players and current legal status of their patents (pending, granted, protected countries, etc.). Recent IP collaborations (patent co-filings) and IP transfers (change in ownership). Focus on key players' patent portfolio.





RF GaN

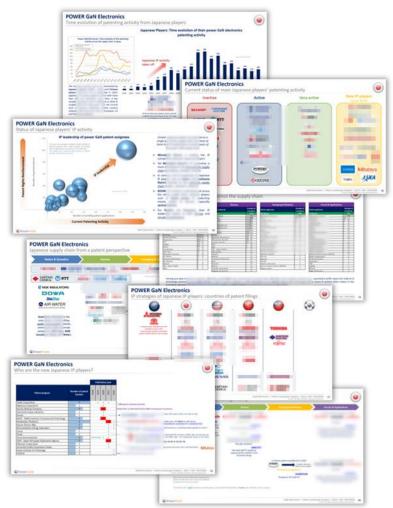
RE GaN Electronic

بأنآ أنا أنسب

SANJOIN

IP dynamics, IP supply chain, IP strategies of players, main technical challenges, IP newcomers





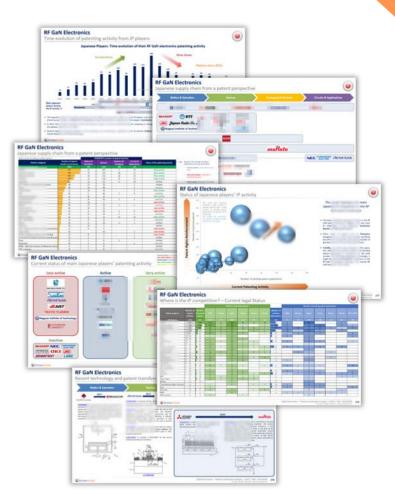
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JAPANESE PLAYERS

Time evolution of patenting activity. Supply chain from a patent perspective. Status of players' IP activity. Main patent assignees. Most active IP players and new entrants. Main technical challenges addressed by IP players. IP strategies of players and current legal status of their

patents (pending, granted, protected countries, etc.). Recent IP collaborations (patent co-filings) and IP transfers (change in ownership). Focus on key players' patent portfolio.





IP dynamics, IP supply chain, IP strategies of players, main technical challenges, IP newcomers







EUROPEAN PLAYERS

Time evolution of patenting activity. Supply chain from a patent perspective. Status of players' IP activity. Main patent assignees. Most active IP players and new entrants.

Main technical challenges addressed by IP players. IP strategies of players and current legal status of their patents (pending, granted, protected countries, etc.). Recent IP collaborations (patent co-filings) and IP transfers (change in ownership). Focus on key players' patent portfolio.





SAMADIA

IP dynamics, IP supply chain, IP strategies of players, main technical challenges, IP newcomers





CHINESE PLAYERS Time evolution of patenting activity. Supply chain from a patent perspective. Status of players' IP activity. Main patent assignees. Most active IP players and new entrants. Main technical challenges addressed by IP players. IP strategies of players and current legal status of their patents (pending, granted, protected countries, etc.). Recent IP collaborations (patent co-filings) and IP transfers (change in ownership).

Focus on key players' patent portfolio.



SANJOIN



IP dynamics, IP supply chain, IP strategies of players, main technical challenges, IP newcomers





TAIWANESE PLAYERS

Time evolution of patenting activity. Supply chain from a patent perspective. Status of players' IP activity.

Main patent assignees. Most active IP players and new entrants. Main technical challenges addressed by IP players. IP strategies of players and current legal status of their patents (pending, granted, protected countries, etc.). Recent IP collaborations (patent co-filings) and IP transfers (change in ownership). Focus on key players' patent portfolio.

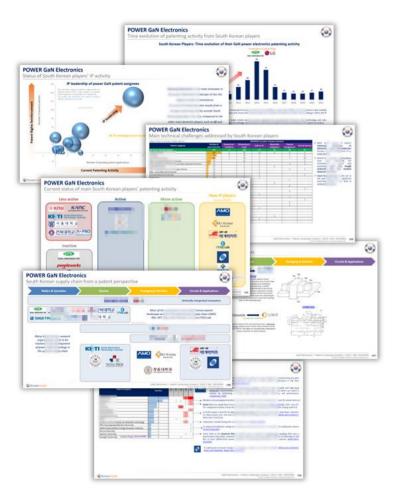


SANJOIN



IP dynamics, IP supply chain, IP strategies of players, main technical challenges, IP newcomers





SOUTH KOREAN PLAYERS

Time evolution of patenting activity. Supply chain from a patent perspective. Status of players' IP activity.

Main patent assignees.

Most active IP players and new entrants. Main technical challenges addressed by IP players. IP strategies of players and current legal status of their patents (pending, granted, protected countries, etc.). Recent IP collaborations (patent co-filings) and IP transfers (change in ownership). Focus on key players' patent portfolio.

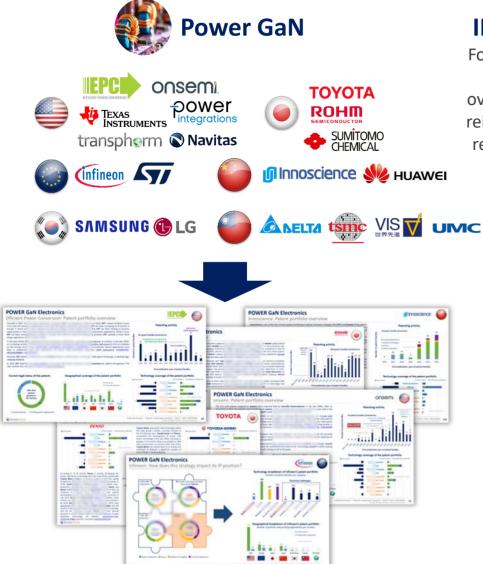




SAMIDIA

IP profile of key players

IP portfolio summary, IP strategy, key patents and recent IP activity



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IP PROFILE OF KEY PLAYERS

For each player, the GaN patent portfolio is statistically analyzed to provide an overview of its strengths, its potential for reinforcement and level of IP activity. The recent patenting activity of the player is then reviewed in light of recent announcements related to GaN and related challenges.





IP dynamics, main patent assignees, most active player, new entrants, technical challenges

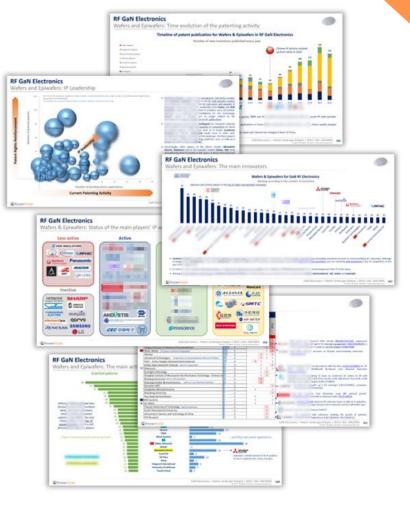




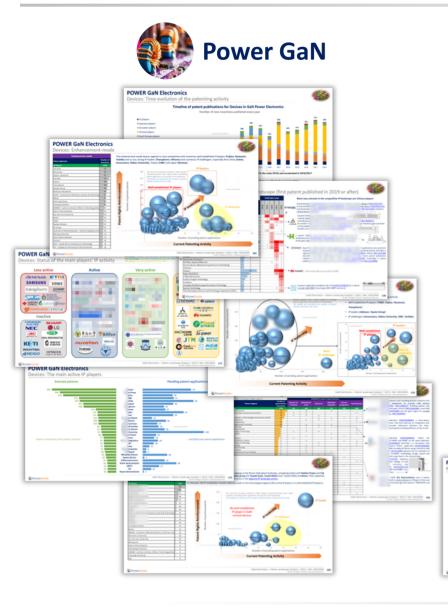
Wafers & Epiwafers

Time evolution of patent publications from US players, Japanese players, European players, etc. Main patent assignees, most active IP players, and new entrants. Current legal status of their patents (pending, granted). Technical challenges addressed by IP players. Main patent assignees and new entrant by technical challenge.





IP dynamics, main patent assignees, most active player, new entrants, technical challenges





Devices

Time evolution of patent publications from US players, Japanese players, European players, etc. Main patent assignees, most active IP players. and new entrants. Current legal status of their patents (pending, granted). Technical challenges addressed by IP players. Main patent assignees and new entrant by technical challenge. **Patent litigation** Innoscience OWER GaN Electronic POWER GaN Electronics POWER GaN Electronics OWER GaN Electro



IP dynamics, main patent assignees, most active player, new entrants, technical challenges







Modules & Packaging

Time evolution of patent publications from US players, Japanese players, European players, etc. Main patent assignees, most active IP players, and new entrants. Current legal status of their patents (pending, granted). Technical challenges addressed by IP players. Main patent assignees and new entrant by technical challenge.





IP dynamics, main patent assignees, most active player, new entrants, technical challenges



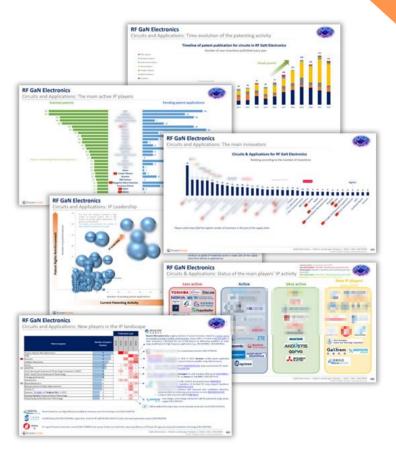




Circuits & Applications

Time evolution of patent publications from US players, Japanese players, European players, etc. Main patent assignees, most active IP players, and new entrants. Current legal status of their patents (pending, granted). Technical challenges addressed by IP players. Main patent assignees and new entrant by technical challenge.





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2.1 Products are sent by email to the Buyer:

- within [1] month from the order for Products already released: or

- within a reasonable time for Products ordered prior to their effective release. In this case, the Seller shall progress.

2.2 Some weeks prior to the release date the Seller can propose a pre-release discount to the Buyer. The Seller shall by no means be responsible for any delay in respect of article 2.2 above, and including in 4.6 In the case where, after inspection, it is acknowledged that the Products contain defects, the Seller by the other Party. cases where a new event or access to new contradictory information would require for the analyst extra undertakes to replace the defective products as far as the supplies allow and without indemnities or The Seller may, from time to time, update these Terms and Conditions and the Buyer, is deemed to have time to compute or compare the data in order to enable the Seller to deliver a high quality Products.

2.3 The mailing of the Product will occur only upon payment by the Buyer, in accordance with the conditions contained in article 3.

2.4 The mailing is operated through electronic means either by email via the sales department. If the 4.7 The deadlines that the Seller is asked to state for the mailing of the Products are given for information 9. GOVERNING LAW AND JURISDICTION Product's electronic delivery format is defective, the Seller undertakes to replace it at no charge to the only and are not guaranteed. If such deadlines are not met, it shall not lead to any damages or cancellation 9.1 Any dispute arising out or linked to these Terms and Conditions or to any contract (orders) entered into download or receipt of the Product.

2.5 The person receiving the Products on behalf of the Buyer shall immediately verify the quality of the first down payment to the exclusion of any further damages. Products and their conformity to the order. Any claim for apparent defects or for non-conformity shall be 4.8 The Seller does not make any warranties, express or implied, including, without limitation, those of and Conditions.

produce sufficient evidence of such defects

done by signing the purchase order which mentions "I hereby accept Knowmade's Terms and Conditions of delivery. Any Product returned to the Seller without providing prior information to the Seller as required guarantee that any Product will be free from infection. under article 2.5 shall remain at the Buyer's risk

"Intellectual Property Rights" ("IPR") means any rights held by the Seller in its Products, including any time to time. The effective price is deemed to be the one applicable at the time of the order

BIC or SWIFT code: CCBPERPPMAR

case the need of down payments will be mentioned on the order

particular written agreement. If the Buyer fails to pay within this time and fails to contact the Seller, the - Information storage and retrieval systems: latter shall be entitled to invoice interest in arrears based on the annual rate Refi of the «RCF» + 7 points in accordance with article L 441-6 of the French Commercial Code. Our publications (report, database, tool...) - use in any timesharing, service bureau, bulletin board or similar arrangement or public display: are delivered only after reception of the payment.

4. LIABILITIES

4.1 The Buyer or any other individual or legal person acting on its behalf, being a business user buying the consequences in their entirety. 1.1 The Contracting Parties undertake to observe the following general conditions when agreed by the Products for its business activities, shall be solely responsible for choosing the Products and for the use and 6.4 The Buyer shall define within its company point of contact for the needs of the contract. This person will

4.2 The Seller shall only be liable for (i) direct and (ii) foreseeable pecuniary loss, caused by the Products or

not limited to, damages for loss of profits, business interruption and loss of programs or information) arising out of the use of or inability to use the Seller's website or the Products, or any information provided may be borne by the Seller, following this decision. on the website. or in the Products:

thereof

4.4 All the information contained in the Products has been obtained from sources believed to be reliable The Seller does not warrant the accuracy, completeness adequacy or reliability of such information, which

cannot be guaranteed to be free from errors.

the liability of the Seller, provided that the Seller ensures the substituted Product is similar to the Product Buyer. initially ordered.

guaranteed for a maximum of two months starting from the delivery date. Any replacement is excluded for in due time. any event as set out in article 5 below.

information from the Seller. In such case only, the Buyer shall be entitled to ask for a reimbursement of its which shall have exclusive jurisdiction upon such issues.

sent in writing to the Seller within 8 days of receipt of the Products. For this purpose, the Buyer agrees to saleability and fitness for a particular purpose, with respect to the Products. Although the Seller shall take

reasonable steps to screen Products for infection of viruses, worms, Trojan horses or other codes "Acceptance": Action by which the Buver accepts the terms and conditions of sale in their entirety. It is 2.6 No return of Products shall be accepted without prior information to the Seller, even in case of delayed containing contaminating or destructive properties before making the Products available, the Seller cannot

5. FORCE MAIEURE

The Seller shall not be liable for any delay in performance directly or indirectly caused by or resulting from 3.1 Prices are given in the orders corresponding to each Product sold on a unit basis or corresponding to acts of nature, fire, flood, accident, riot, war, government intervention, embargoes, strikes, labor annual subscriptions. They are expressed to be inclusive of all taxes. The prices may be reevaluated from difficulties, equipment failure, late deliveries by suppliers or other difficulties which are beyond the control. and not the fault of the Seller.

6 PROTECTION OF THE SELLER'S IPR

6.1 All the IPR attached to the Products are and remain the property of the Seller and are protected under French and international copyright law and conventions

6.2 The Buyer agreed not to disclose convirgence under redistribute resell or publish the Product or any To ensure the payments, the Seller reserves the right to request down payments from the Buyer. In this part of it to any other party other than employees of its company. The Buyer shall have the right to use the Products solely for its own internal information purposes. In particular, the Buyer shall therefore not use

- Recordings and re-transmittals over any network (including any local area network):

- Posting any Product to any other online service (including bulletin boards or the Internet):

- Licensing, leasing, selling, offering for sale or assigning the Product.

6.3 The Buyer shall be solely responsible towards the Seller of all infringements of this obligation, whether this infringement comes from its employees or any person to whom the Buyer has sent the Products and shall personally take care of any related proceedings and the Buyer shall bear related financial

Buver and the Seller. Any additional, different, or conflicting terms and conditions in any other documents interpretations he makes of the documents it purchases, of the results he obtains, and of the advice and be the recipient of each new report in PDF format. This person shall also be responsible for respect of the copyrights and will guaranty that the Products are not disseminated out of the company.

7. TERMINATION

7.1 If the Buyer cancels the order in whole or in part or postpones the date of mailing, the Buyer shall accepts these conditions of sales when signing the purchase order which mentions "I hereby accept a) damages of any kind. including without limitation, incidental or consequential damages (including, but indemnify the Seller for the entire costs that have been incurred as at the date of notification by the Buyer of such delay or cancellation. This may also apply for any other direct or indirect consequential loss that

> 7.2 In the event of breach by one Party under these conditions or the order, the non-breaching Party may b) any claim attributable to errors, omissions or other inaccuracies in the Product or interpretations send a notification to the other by recorded delivery letter upon which, after a period of thirty (30) days without solving the problem, the non-breaching Party shall be entitled to terminate all the pending orders. without being liable for any compensation

8. MISCELLANEOUS

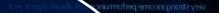
4.5 All the Products that the Seller sells may, upon prior notice to the Buyer from time to time be modified All the provisions of these Terms and Conditions are for the benefit of the Seller itself, but also for its use its best endeavours to inform the Buyer of an indicative release date and the evolution of the work in by or substituted with similar Products meeting the needs of the Buyer. This modification shall not lead to licensors, employees and agents. Each of them is entitled to assert and enforce those provisions against the

Any notices under these Terms and Conditions shall be given in writing. They shall be effective upon receipt

compensation of any kind for labor costs, delays, loss caused or any other reason. The replacement is accepted the latest version of these terms and conditions, provided they have been communicated to him

Buver provided that it is informed of the defective formatting within 90 days from the date of the original of the orders. exceeding [4] months from the stated deadline, without in application of these Terms and Conditions shall be settled by the French Commercial Courts of Grasse,

9.2 French law shall govern the relation between the Buyer and the Seller, in accordance with these Terms



1 June 2008

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KNOWMADE PURPOSE

Turning **patent information** and **scientific literature** into actionable insights, providing high added value reports for **decision-makers** working in **R&D**, **Innovation Strategy**, **Intellectual Property**, and **Marketing**

Competitive landscape | Technology trends | Opportunities / Risks | R&D and IP strategy

Patent your inventions Assert your patents and defend your position (licensing/litigation) Evaluate the risks to infringe patents Understand, anticipate and evaluate the competitive landscape and current technology developments

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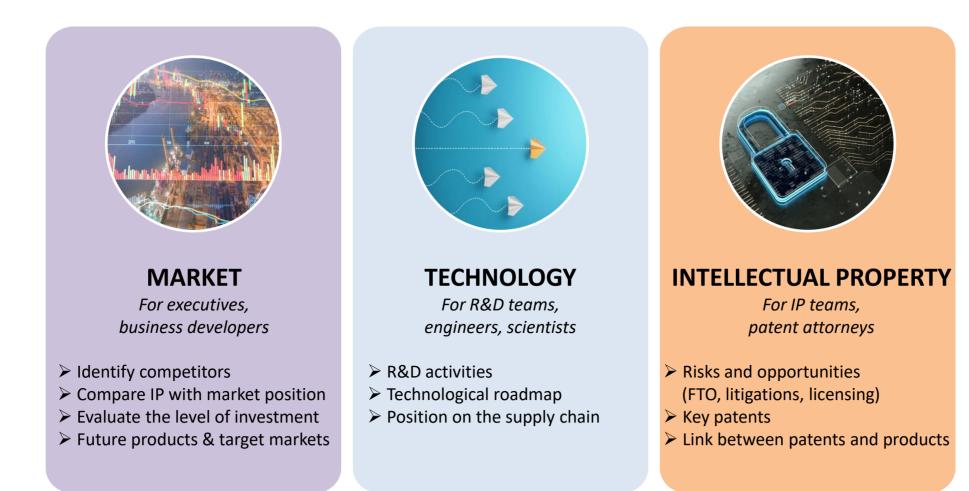
Patent landscape Monitoring service Patent portfolio analysis

KnowMade

Innovation Strategy

Technology scouting Scientific literature analysis

WHAT INFORMATION CAN YOU GET ?



CUSTOM SERVICES

(Tailor-made analysis)

To meet your needs and budget/lead time constraints

> Specific and dedicated report.

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- PDF file with analyses.
- Excel file with data.
- Access to the analyst.

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To understand the competitive landscape and explore the emerging ecosystems and new technologies

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- > Open discussion with analyst.

FormatPDF file with analyses.Excel file with patent data.Direct access to the analyst.

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To get unique information about industry and technology

Analyst point of view about industry news (product release, M&A, start-up, fund-raising, etc.) from a patent perspective.

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MAIN FIELDS OF EXPERTISE

SEMICONDUCTORS

- > Materials & Substrates
- Power electronics
- RF & Wireless datacom
- MEMS, Sensing & Imaging
- Photonics, Lighting & Display
- > Memory
- Packaging

ENERGY

- Batteries
- ➢ Fuel-cells
- Solar PV
- Power management



HEALTHCARE

- > Therapeutic tools
- Diagnostics and Theragnostics
- Medical devices and imaging
- Drug discovery and delivery

AGRI-FOOD

- Food processing & formulation
- Vegan food
- Next-gen packaging
- > Agriculture 4.0



SEMICONDUCTORS

Expertise



Power electronics

- Wide bandgap semiconductors
- Power devices and IC
- Power modules
- Power applications

RF & Wireless communications

- > RF substrate & epiwafers
- > RF devices (SAW, BAW, PA/LNA, etc.), RFIC, MMIC
- ➢ RF front-end module, RF packaging
- > MIMO, beamforming, carrier aggregation
- > 5G & 6G networks, Radar, mm-waves, microwaves, THz

MEMS, Sensing & Imaging

- MEMS sensors and actuators
- 3D imaging and sensing (ToF, CIS, thermal imaging, LiDAR, imaging Radar, event-based camera, etc.)
- > AI/ML, sensor data fusion



SEMICONDUCTORS

from materials and devices to circuits, packaging and modules/systems



Memory

- > SRAM, DRAM, flash
- 3D-stacked memories
- Emerging non-volatile memories (MRAM, PCM, RRAM, etc.)
- Embedded NVM

Photonics, Lighting & Display

- Optoelectronics & optical components (LED, OLED, laser, optical transceivers, waveguides, metasurfaces, etc.)
- > Photonic crystal, photonic IC, silicon photonics
- > Optical communications, AR/VR, quantum

Advanced packaging

- Fan-Out WLP/PLP, 2.5D/3D IC
- > SiP, SoC, Chiplets
- TSV, μbumps, interposer, interconnect bridge, hybrid bonding

Materials & Substrates

- Compound semiconductors
- Engineered substrates
- ➢ Epiwafers



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